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JAN 19 1961  
CLAIMS:

1. A heat-treating method for a packaging product, comprising:

providing a packaging product formed by  
5 enclosing a content material within a packaging material comprising at least a layer of hydrophilic resin, and

heat-treating the packaging product with hot water,

10 wherein the hot water is caused to contain a water-soluble compound.

2. A heat-treating method according to Claim 1, wherein the hot water has a temperature of 60-100°C  
15 to effect a boiling heat-treatment.

3. A heat-treating method according to Claim 1, wherein the hot water has a temperature exceeding 100°C to effect a retort heat-treatment.

20 4. A heat-treating method according to any of Claim 1 to 3, wherein the hot water contains the water-soluble compound at a concentration exceeding 0.1 wt.%.

25 5. A heat-treating method according to any of Claims 1 to 3, wherein the hot water contains the

water-soluble compound at a concentration of at least 1 wt.%.

6. A heat-treating method according to any of  
5 Claims 1 to 5, wherein the water-soluble compound is an inorganic electrolyte.

7. A heat-treating method according to Claim 6,  
wherein the water-soluble compound is a  
10 water-soluble inorganic salt.

8. A heat-treating method according to Claim 7,  
wherein the water-soluble compound is a chloride  
selected from the group consisting of sodium chloride,  
15 magnesium chloride, and potassium chloride.

9. A heat-treating method according to Claim 8,  
wherein the water-soluble compound is sodium  
chloride.

20 10. A heat-treating method according to any of  
Claims 1 to 5, wherein the water-soluble compound is  
a water-soluble organic compound.

25 11. A heat-treating method according to Claim  
10, wherein the water-soluble compound is a  
water-soluble alcohol.

12. A heat-treating method according to any of Claims 1 to 11, wherein the hydrophilic resin layer is a gas-barrier resin layer.

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13. A heat-treating method according to Claim 12, wherein the gas-barrier resin is selected from the group consisting of ethylene-vinyl alcohol copolymer, polyamide (co-)polymers, and aliphatic ester

10 (co-)polymers.

14. A heat-treating method according to Claim 13, wherein the gas-barrier resin is selected from the group consisting ethylene-vinyl alcohol copolymer, polymetaxylylene adipamide and glycolic acid

15 (co-)polymer.

15. A heat-treating method according to any of Claims 1 to 14, wherein the packaging material has a multi-layer structure.

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16. A heat-treating method according to Claim 15, wherein the hydrophilic resin layer is disposed as a surface layer contacting the hot water of the

25 packaging material.

17. A heat-treating method according to Claim

15, wherein the hydrophilic resin layer is disposed as an inner layer not directly contacting the hot water of the packaging material.

5           18. A heat-treating method according to Claim 17, wherein the gas-barrier resin is glycolic acid (co-)polymer.

10           19. A packaged product, which has been heat-treated by a heat-treating method according to any one of Claims 1 to 18.

15           20. A packaged product according to Claim 19, wherein the heat-treated packaging material has a haze below 20%.

20           21. A heat-treated packaged product, comprising a heat-treated packaging material having a multi-layer structure including an inner layer of a hydrophilic gas-barrier resin layer selected from the group consisting of ethylene-vinyl alcohol copolymer and glycolic acid (co-)polymer, and a content material enclosed within the packaging material, wherein the heat-treated packaging material has a  
25           haze below 20%.

22. A packaged product according to Claim 21,

wherein the hydrophilic gas-barrier resin is  
ethylene-vinyl alcohol copolymer.

23. A packaged product according to Claim 21,  
5 wherein the hydrophilic gas-barrier resin is glycolic  
acid (co-)polymer.

24. A packaged product according to any of  
Claims 19 to 23, wherein the packaged material has  
10 been subjected to a heat-shrinking treatment during  
the heat treatment.